

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2023/0230998 A1

Jul. 20, 2023 (43) **Pub. Date:**

(54) BACKSIDE-ILLUMINATED IMAGE SENSOR AND METHOD OF MANUFACTURING

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Appl. No.: 18/067,659 (21)

(22)Filed: Dec. 16, 2022

(30)Foreign Application Priority Data

Jan. 19, 2022 (KR) 10-2022-0007669

Publication Classification

(51) Int. Cl. H01L 27/146 (2006.01)

(52) U.S. Cl. CPC H01L 27/1464 (2013.01); H01L 27/14621

(2013.01); H01L 27/14636 (2013.01); H01L 27/14627 (2013.01); H01L 27/14685

(2013.01)

(57)**ABSTRACT**

A backside-illuminated image sensor and a method of manufacturing the same are disclosed. The backside-illuminated image sensor is capable of improving sensitivity by including a scattering layer in a substrate that may result in incident light having a path greater than the thickness of the substrate and, simultaneously, of additionally enhancing light sensitivity with respect to a specific wavelength or wavelength band of light passing through one of a plurality of different color filters by a varying depth or thickness of the scattering layer for each unit pixel in the image sensor.

